

December 2014

# FCPF260N65FL1

# N-Channel SuperFET® II FRFET® MOSFET

**650 V, 15 A, 260 m**Ω

## **Features**

- 700 V @T<sub>J</sub> = 150°C
- $R_{DS(on)} = 220 \text{ m}\Omega \text{ (Typ.)}$
- Ultra Low Gate Charge (Typ. Q<sub>g</sub> = 46 nC)
- Low Effective Output Capacitance (Typ. C<sub>oss(eff.)</sub> = 223 pF)
- · 100% Avalanche Tested
- · RoHS Compliant

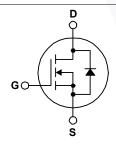
# **Applications**

- LCD / LED / PDP TV Telecom / Server Power Supplies
- Solar Inverter
   AC DC Power Supply

# **Description**

SuperFET® II MOSFET is Fairchild Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently, SuperFET II MOSFET is very suitable for the switching power applications such as PFC, server/telecom power, FPD TV power, ATX power and industrial power applications. SuperFET II FRFET® MOSFET's optimized body diode reverse recovery performance can remove additional component and improve system reliability.





# Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

Symbol		Parameter	FCPF260N65FL1	Unit
V <sub>DSS</sub>	Drain to Source Voltage		650	V
\ /	Cata ta Causaa Valtana	- DC	±20	V
/ <sub>GSS</sub> Gate to Source Voltage		- AC (f > 1 Hz	±30	V
Drain Current		- Continuous (T <sub>C</sub> = 25°C)	15	^
I <sub>D</sub> Drain Current	Drain Current	- Continuous (T <sub>C</sub> = 100°C)	9.5	A
I <sub>DM</sub>	Drain Current	45	Α	
E <sub>AS</sub>	Single Pulsed Avalanche Energy	293	mJ	
I <sub>AR</sub>	Avalanche Current (Note 1)		3	Α
E <sub>AR</sub>	Repetitive Avalanche Energy	(Note 1	0.36	mJ
ما ( ماد	MOSFET dv/dt		100	1//
dv/dt	Peak Diode Recovery dv/dt	(Note 3	50	V/ns
		$(T_C = 25^{\circ}C)$	36	W
$P_{D}$	Power Dissipation  - Derate Above 25°C		0.29	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperation	-55 to +150	°C	
TL	Maximum Lead Temperature for	Soldering, 1/8" from Case for 5 Seconds	300	°C

## **Thermal Characteristics**

Symbol	Parameter	Parameter FCPF260N65FL1				
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	3.5	°C/W			
$R_{ heta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	*C/VV			

# **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCPF260N65FL1	FCPF260N65F	TO-220F	Tube	N/A	N/A	50 units

# **Electrical Characteristics** $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	cteristics					
D\/	Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 10 \text{ mA}, T_J = 25^{\circ}\text{C}$	650	-	-	V
BV <sub>DSS</sub> Drain to Source Breakdown Voltage	Dialii to Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 10 \text{ mA}, T_J = 150^{\circ}\text{C}$	700	-	-	V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 10 mA, Referenced to 25°C	-	0.72	-	V/°C
1	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 650 V, V <sub>GS</sub> = 0 V	-	-	10	
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 520 \text{ V}, V_{GS} = 0 \text{ V}, T_{C} = 125^{\circ}\text{C}$	-	40	-	μА
I <sub>GSS</sub>	Gate to Body Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	±100	μΑ

### On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}$ , $I_D = 1.5 \text{ mA}$	3	-	5	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 7.5 \text{ A}$	-	220	260	mΩ
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = 20 \text{ V}, I_{D} = 7.5 \text{ A}$	ı	14.2	-	S

# **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V 400 V V 0 V	-	1760	2340	pF
C <sub>oss</sub>	Output Capacitance	$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1 MHz	-	59	80	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 1 101112	-\	1.0	-	pF
Coss	Output Capacitance	V <sub>DS</sub> = 380 V, V <sub>GS</sub> = 0 V, f = 1 MHz	- \	34	-	pF
C <sub>oss(eff.)</sub>	Effective Output Capacitance	V <sub>DS</sub> = 0 V to 400 V, V <sub>GS</sub> = 0 V		223	-	pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10V	V <sub>DS</sub> = 380 V, I <sub>D</sub> = 7.5 A,	-	46	60	nC
$Q_{gs}$	Gate to Source Gate Charge	V <sub>GS</sub> = 10 V	-	9.6	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge	(Note 4)	-	20	-	nC
ESR	Equivalent Series Resistance	f = 1 MHz	-	0.52	-	Ω

# **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time		- /	21.7	54	ns
t <sub>r</sub>		$V_{DD} = 380 \text{ V}, I_D = 7.5 \text{ A},$	-/	10.5	32	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_g = 4.7 \Omega$	<i>j</i> -	54	118	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4)	/ -	5.8	22	ns

# **Drain-Source Diode Characteristics**

Is	Maximum Continuous Drain to Source Diod	Maximum Continuous Drain to Source Diode Forward Current			15	Α
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current			-	45	Α
$V_{SD}$	Drain to Source Diode Forward Voltage $V_{GS} = 0 \text{ V}, I_{SD} = 7.5 \text{ A}$		-	-	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 7.5 A,	-	98	- ,	ns
Q <sub>rr</sub>	Reverse Recovery Charge $dI_F/dt = 100 \text{ A}/\mu\text{s}$		-	450	-	nC

#### Notes:

- 1. Repetitive rating: pulse width limited by maximum junction temperature.
- 2.  $I_{AS}$  = 3 A,  $R_{G}$  = 25  $\Omega$ , Starting  $T_{J}$  = 25°C
- 3. I  $_{SD} \leq 7.5$  A, di/dt  $\leq 200$  A/µs, V  $_{DD} \leq 380$  V, Starting T  $_{J}$  =  $25^{\circ}C$
- 4. Essentially independent of operating temperature.

# **Typical Performance Characteristics**

Figure 1. On-Region Characteristics

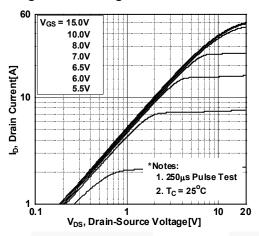


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

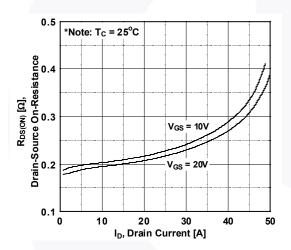


Figure 5. Capacitance Characteristics

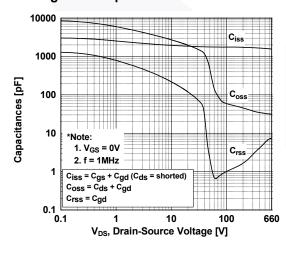


Figure 2. Transfer Characteristics

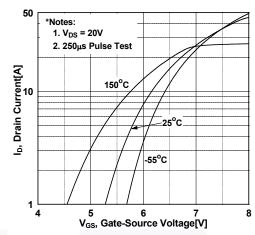


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

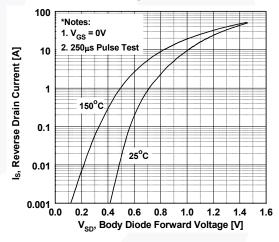
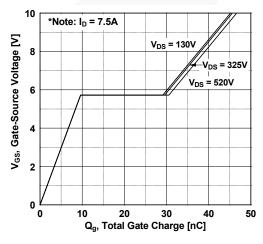


Figure 6. Gate Charge Characteristics



# Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

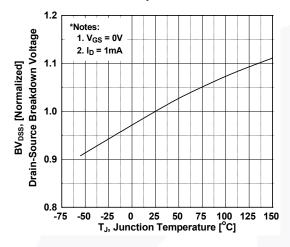


Figure 9. Maximum Safe Operating Area

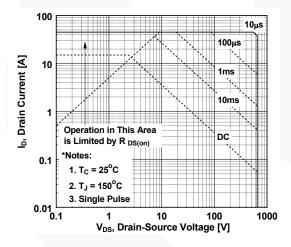


Figure 11. Eoss vs. Drain to Source Voltage

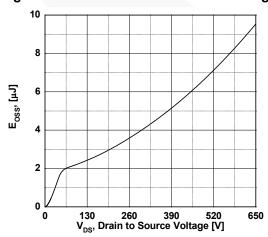


Figure 8. On-Resistance Variation vs. Temperature

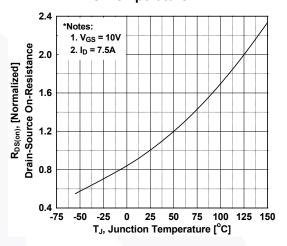
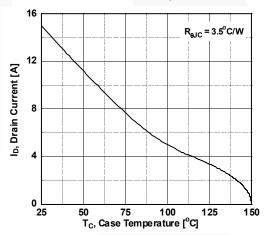
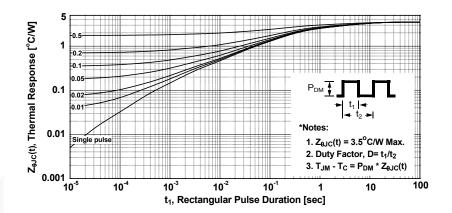


Figure 10. Maximum Drain Current vs. Case Temperature



# **Typical Performance Characteristics** (Continued)

Figure 12. Transient Thermal Response Curve



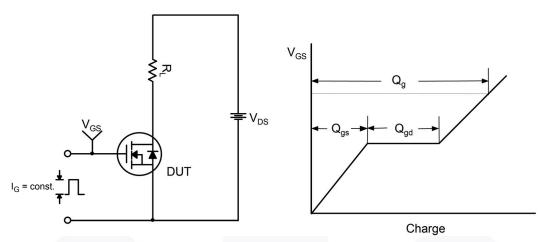


Figure 13. Gate Charge Test Circuit & Waveform

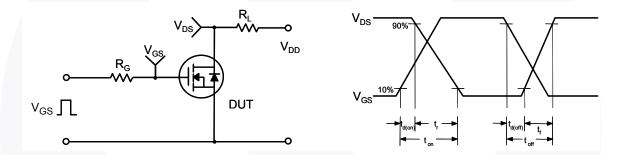


Figure 14. Resistive Switching Test Circuit & Waveforms

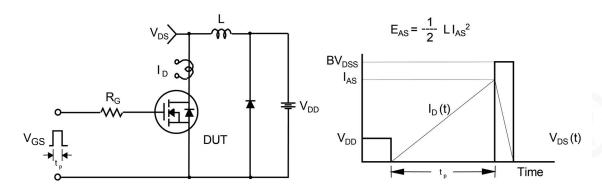


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

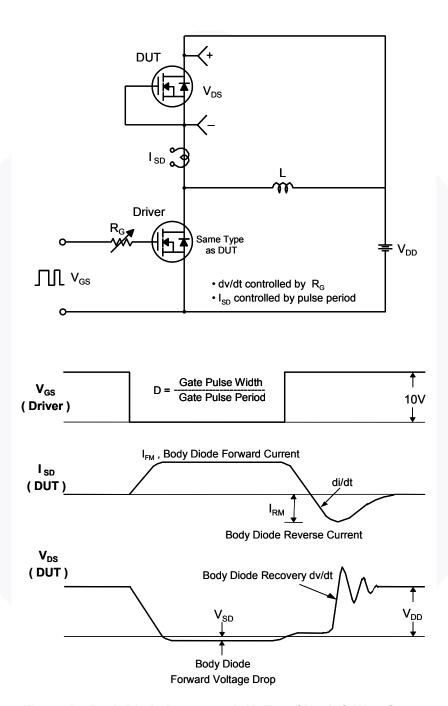


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms

# **Mechanical Dimensions**

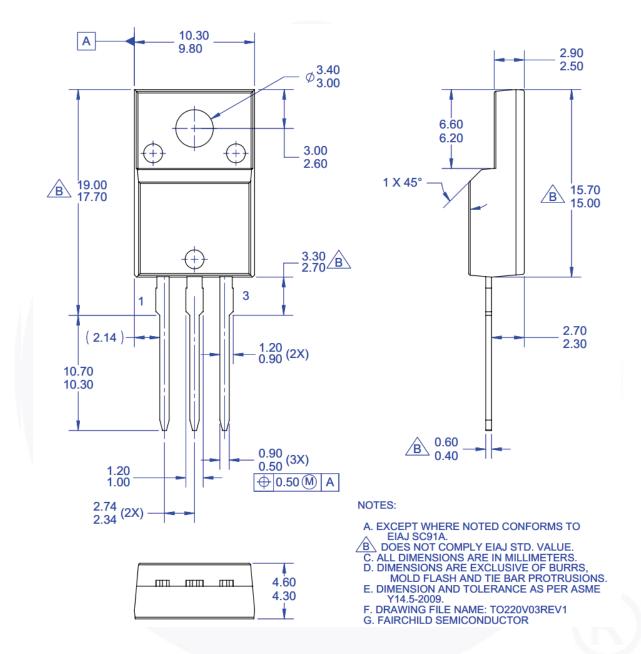


Figure 17. TO220, Molded, 3LD, Full Pack, EIAJ SC91, Takcheong

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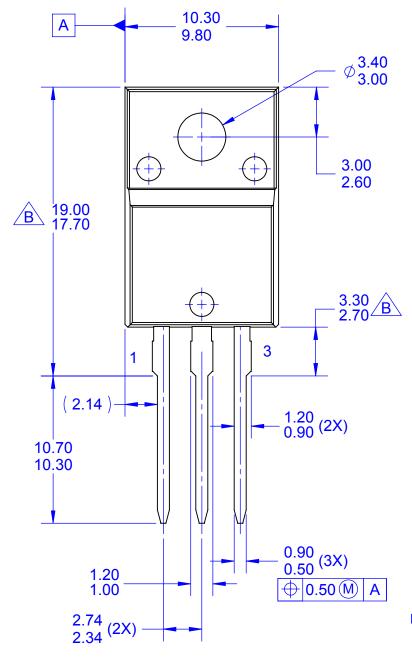
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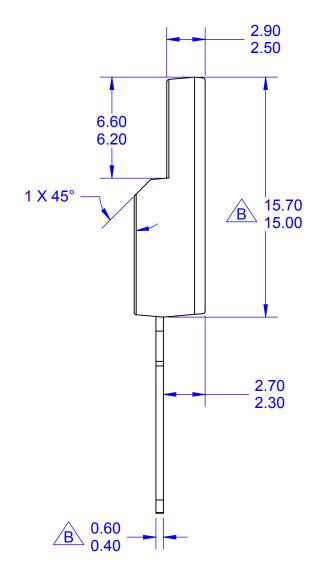
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Rev. 177

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